

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Original) A circuit device comprising:
a first circuit element having a hollow inside;
a plurality of second circuit elements electrically connected to the first circuit element; and
sealing resin for covering the first and second circuit elements,
wherein the distances by which the first circuit element is separated from the second circuit elements are longer than those by which the second circuit elements are separated from each other.
2. (Original) The circuit device according to claim 1, wherein the second circuit elements are located closer to a central portion of the sealing resin than the first circuit element is.
3. (Original) The circuit device according to claim 1, wherein the first circuit element is located closer to a peripheral portion of the sealing resin than the second circuit elements are.
4. (Original) The circuit device according to claim 1, wherein the first circuit element is a SAW filter.
5. (Currently Amended) A circuit device comprising:
a first circuit element having a hollow inside therein;

a plurality of second circuit elements electrically connected to the first circuit element; and

a sealing resin for covering the first and second circuit elements,
wherein the first circuit element is located closer to a peripheral portion of the sealing resin than the second circuit element is disposed in a more peripheral area of the sealing resin than the second circuit elements, and a separated distance between the first and second circuit elements is longer than a separated distance between the second circuit elements.

6. (Original) The circuit device according to claim 5, wherein the first circuit element is located in a vicinity of an end portion of the sealing resin in a longitudinal direction, and the second circuit element is located in a vicinity of a central portion of the sealing resin in the longitudinal direction.

7. (Deleted)

8. (Original) The circuit device according to claim 5, wherein the first circuit element is a SAW filter.

9. (Currently Amended) A circuit device, comprising:
a first circuit element fixed to a first land, the first circuit element and having a hollow inside therein;
a second circuit element fixed to a second land located in a vicinity of a central portion away from the first land separated from the first land and fixed to a second land disposed in a vicinity of a central area;
a first lead of which whose one end is led out to an outside and of which the other end is connected to any one of the first and or second circuit elements;
a second lead for connecting the first and second circuit elements; and
a third lead extending in a manner of connecting the first and second lands and formed to have a narrower width than those of the first and second lands; and
a sealing resin for sealing each of the circuit elements and each of the leads.

10. (Original) The circuit device according to claim 9, wherein the first circuit element is a SAW filter.

11. (Original) The circuit device according to claim 9, wherein the second circuit element is any one of a semiconductor element for processing any one of a video signal and an image signal, a semiconductor element for processing information associated with the video signal, and a CCD for delaying an electrical signal.

12. (Original) The circuit device according to claim 9, wherein any one of the first and second circuit elements is connected to any one of the first and second leads through a fine metal wire.

13. (Original) A method of manufacturing a circuit device, comprising the steps of:

placing a first circuit element having a hollow inside and a second circuit element electrically connected to the first circuit element in a cavity of a molding die; and

sealing the first and second circuit elements with resin by filling sealing resin from a gate into the cavity,

wherein the first circuit element is located farther away from the gate than the second circuit element is.

14. (Original) The method according to claim 13,
wherein the cavity forms a long and narrow space,
the gate is formed in an end portion of the cavity in a longitudinal direction, and
the first circuit element is located in a vicinity of an end portion opposite to the gate inside the cavity.

15. (Original) The method according to claim 13, wherein thermosetting resin is adopted as the sealing resin.

16. (New) A circuit device, comprising:
a first circuit element having a hollow therein;
a second circuit element electrically connected to the first circuit element; and
a sealing resin covering the first and second circuit elements,
wherein the first and second circuit elements are sealed by enclosing the sealing resin from a gate in a cavity molded with a mold, and a distance between the first circuit element and the gate is longer than a distance between the second circuit element and the gate.

17. (New) The circuit device according to claim 16, wherein the gate is positioned at an edge in a lengthwise direction of the sealing resin, and the first circuit element is disposed in a vicinity of the edge opposed to the gate.

18. (New) The circuit device according to claim 16, wherein the plurality of second circuit elements are disposed in a vicinity of a central area of the sealing resin, and the first circuit element is disposed in a more peripheral area than the second circuit elements.